

# A Warm Welcome to Two New T-ED Editors

I AM delighted to announce the appointments to the T-ED Editorial Board of Professor Kyung Cheol Choi of Korean Advanced Institute of Science and Technology, Yuseong, Daejeon, South Korea, in the area of Display Technology, and Professor Muhannad Bakir of Georgia Tech, Atlanta, GA, USA, in the area of interconnects and packaging. Both of these gentlemen are recognized experts in these rapidly evolving fields, and are fine additions to the T-ED Editorial Board.

Short biographies of their accomplishments are given below. Welcome aboard!

JOHN D. CRESSLER  
T-ED *Editor-in-Chief*  
Georgia Tech  
Atlanta, GA



**Kyung Cheol Choi** received the B.S. degree from the Department of Electrical Engineering, Seoul National University, Seoul, Korea, and the M.S. and Ph.D. degrees in plasma engineering from Seoul National University, in 1986, 1988, and 1993, respectively.

He was involved with researching and developing display devices with the Institute for Advanced Engineering, Spectron Corporation of America, Summit, NJ, USA, and Hyundai Electronics Industries, from 1993 to 1999. From 2000 to 2004, he was an Associate Professor with the Department of Electronics Engineering, Sejong University, Seoul. He was in charge of the Information Display Research Center supported by the Korean Ministry of Information and Communication. Since 2005, he has been with the Department of Electrical Engineering, Korea Advanced Institute of Science and Technology (KAIST), Daejeon, Korea, where he was an Associate Professor and is currently a KAIST Chair Professor. Since 2007, he has been in charge of the Center for Advanced Flexible Display Convergence supported by the Korean Ministry of Education, Science, and Technology. He has been in charge of LG Display-KAIST

Cooperation Center since 2010. His current research interests include flexible and transparent displays, organic light-emitting diodes, and surface plasmon applications for electronic devices and displays.

Dr. Choi is a member of the Society for Information Display and the Korean Information Display Society. He was an Associate Editor of the IEEE/OSA Journal of Display Technology from 2005 to 2010.



**Muhannad S. Bakir** received the B.E.E. (*summa cum laude*) degree from Auburn University, Auburn, AL, USA, and the M.S. and Ph.D. degrees in electrical and computer engineering from the Georgia Institute of Technology (Georgia Tech), in 1999, 2000, and 2003, respectively.

He is currently an Associate Professor and the ON Semiconductor Junior Professor in the School of Electrical and Computer Engineering, Georgia Tech. He is the co-editor (with James D. Meindl) of a book entitled *Integrated Interconnect Technologies for 3D Nanoelectronic Systems* (Artech House, 2009) and is the author/co-author of more than 110 journal publications and conference proceedings, 14 U.S. patents, and the presenter of two conference tutorials, including an invited tutorial on 3-D technology at the International Solid-State Circuits Conference in 2007. His current research interests include 3-D electronic systems, advanced interconnection and packaging, and nanofabrication technology.

Dr. Bakir is the recipient of the Intel Early Career Faculty Honor Award in 2013, the DARPA Young Faculty Award in 2012, and the IEEE CPMT Society Outstanding Young Engineer Award in 2011, and was an Invited Participant at the National Academy of Engineering Frontiers of Engineering Symposium in 2012. He is also a recipient of the Semiconductor Research Corporation Inventor Recognition Awards in 2002, 2005, and 2009, and 12 conference and student paper awards, including one from the IEEE Custom Integrated Circuits Conference, five from the IEEE Electronic Components and Technology Conference, and three from the IEEE International Interconnect Technology Conference. He was an Associate Editor of the IEEE TRANSACTIONS ON COMPONENTS, PACKAGING, AND MANUFACTURING TECHNOLOGY, and was a Guest Editor of the June 2011 SPECIAL ISSUE OF IEEE JOURNAL OF SELECTED TOPICS IN QUANTUM ELECTRONICS. He is also a member of the International Technology Roadmap for Semiconductors technical working group for Assembly and Packaging.